```
359/224.ccls. USPAT; US-PGPUB 2004/07/12 11:01
              569
BRS
      L2
             ((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or method)
       199
BRS
with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and optic$6 and
SiO$6 USPAT; US-PGPUB 2004/01/07 11:14
             ((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or method)
BRS
       536
with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and optic$6 and
                     USPAT; US-PGPUB 2004/01/07 11:15
(SiO$6 or silicon)
              (((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
       172
BRS
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))
              2004/01/07 11:40
PGPUB
              ((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
BRS
       48
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and (optic$6
                    USPAT; US-PGPUB 2004/01/07 11:18
with (ax$6 or port))
              (((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
BRS
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and (optic$6
                                   USPAT; US-PGPUB 2004/01/07 11:36
with (ax$6 or port))) and cavit$6
                                          USPAT; US-PGPUB 2004/01/07 11:35
              sacrificial with etch-stop
BRS
       66
              (((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
BRS
       22
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and (optic$6
with (ax$6 or port))) and cavit$6) and (sacrificial with layer$6)
                                                               USPAT; US-PGPUB
       2004/01/07 11:41
              ((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
BRS
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and ((mirror or
                            USPAT; US-PGPUB 2004/01/07 11:53
reflect$8) with cavit$6)
       0
              (coat$6 with layer$6) and (MEMS or MOEMS) and ((process or method)
BRS
       788
with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)
                                                                       USPAT; US-
              2004/01/08 15:11
PGPUB
              (((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
BRS
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
 optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and ((mirror or
reflect$8) with cavit$6)) and (sacrificial with layer$6)
                                                         USPAT; US-PGPUB
        2004/01/07 11:54
              ((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
 BRS
 method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
 optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and ((mirror or
 reflect$8) with (cavit$6 or filter or laser)) USPAT; US-PGPUB 2004/01/08 14:42
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(((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
BRS
      34
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and ((mirror or
reflect$8) with (cavit$6 or filter or laser))) and (sacrificial with layer$6) USPAT; US-
             2004/01/07 14:22
PGPUB
                                  USPAT; US-PGPUB 2004/01/07 17:59
             "20020168136"
BRS
      1
       0
             5986796.pn. USPAT; US-PGPUB 2004/01/07 18:14
       1
BRS
       0
                                                       USPAT; US-PGPUB
              "20020168136" and (support with port)
BRS
       1
       2004/01/07 18:18
              5986796.pn. and (mirror same etch$6)
                                                       USPAT: US-PGPUB
BRS
       1
       2004/01/07 18:33
                                                              USPAT; US-PGPUB
              "20020168136" and (etch-stop with optic$6)
BRS
       2004/01/07 21:23
              "20020168136" and (etch$6 with coat$6)
                                                       USPAT; US-PGPUB
BRS
       1
       2004/01/07 21:23
              5986796.pn. and (etch$6 with coat$6)
                                                       USPAT; US-PGPUB
BRS
       2004/01/07 21:22
              5986796.pn. and (etch$6 with coat$6) and (etch$6 with $6stop)
BRS
       USPAT; US-PGPUB 2004/01/07 21:22
                                                       USPAT; US-PGPUB
              "20020168136" and (etch$6 with coat$6)
BRS
       2004/01/07 21:23
              "20020168136" and (etch-stop with optic$6)
                                                              USPAT; US-PGPUB
BRS
       2004/01/07 21:47
              ("20020168136" and (etch$6 with coat$6)) ("20020168136" and (etch-
BRS
stop with optic$6) ) ("20020168136" and (etch$6 with $6stop))
                                                              USPAT; US-PGPUB
       2004/01/07 21:24
                                                       USPAT; US-PGPUB
              "20020168136" and (device near1 layer)
BRS
       2004/01/07 21:26
              "20020168136" and (etch$6 with $6stop)
                                                       USPAT; US-PGPUB
BRS
       2004/01/07 21:28
              "20020168136" and (coat$6 with optic$6) USPAT; US-PGPUB
BRS
       1
       2004/07/02 21:49
              ((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
BRS
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and ((mirror or
reflect$8) with (cavit$6 or filter or laser)) and ((dielectric$6 with (film or coat$6)) same
              USPAT; US-PGPUB 2004/01/08 14:48
 thick$6)
              (((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
 BRS
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and ((mirror or
reflect$8) with (cavit$6 or filter or laser)) and ((dielectric$6 with (film or coat$6)) same
 thick$6)) and metal USPAT; US-PGPUB 2004/01/08 14:49
              (((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
 BRS
 method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
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optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and ((mirror or
reflect$8) with (cavit$6 or filter or laser)) and ((dielectric$6 with (film or coat$6)) same
                                               USPAT; US-PGPUB 2004/01/08
thick$6)) and (metal with (coat$6 or layer$6))
14:52
             (((((coat$6 with layer$6) and (MEMS or MOEMS) and ((process or
BRS
      14
method) with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6)) and
optic$6 and (SiO$6 or silicon)) and (dielectric$6 with (film or coat$6))) and ((mirror or
reflect$8) with (cavit$6 or filter or laser)) and ((dielectric$6 with (film or coat$6)) same
thick$6)) and (metal with (coat$6 or layer$6) with (reflect$6 or mirror$3)) USPAT; US-
              2004/01/08 14:53
PGPUB
             (coat$6 with layer$6) and (MEMS or MOEMS) and ((process or method)
BRS 5
with (mak$6 orfabricat$6 or manufactur$6)) and (etch$8 with layer$6) and (dop$6 with
             USPAT; US-PGPUB 2004/01/08 15:21
curv$7)
              (MEMS or Moems) and (dop$6 with curvature)
                                                             USPAT; US-PGPUB
BRS
      22
       2004/01/08 15:22
              ((MEMS or Moems) and (dop$6 with curvature)) not ((coat$6 with
       19
BRS
layer$6) and (MEMS or MOEMS) and ((process or method) with (mak$6 orfabricat$6 or
manufactur$6)) and (etch$8 with layer$6) and (dop$6 with curv$7))
                                                                    USPAT; US-
              2004/01/08 15:22
PGPUB
                                                2004/07/02 21:15
              "20020126726"
                                  USPAT
BRS
      0
       0
                                  USPAT; US-PGPUB 2004/07/02 21:22
              "20020126726"
BRS
       1
       0
                                   USPAT; US-PGPUB 2004/07/02 21:25
              "20020080504"
BRS
       1
       0
                            USPAT; US-PGPUB 2004/07/02 21:25
              6721098.pn.
BRS
       1
                            USPAT; US-PGPUB 2004/07/02 21:49
              216/24.ccls.
BRS
       641
                                          USPAT; US-PGPUB 2004/07/02 21:50
              216/24.ccls. and "2001"
       179
 BRS
                                          USPAT; US-PGPUB 2004/07/02 21:51
              216/24.ccls. and "2002"
 BRS
        132
                                          USPAT; US-PGPUB 2004/07/02 21:59
              216/24.ccls. and "2004"
        38
 BRS
                                          USPAT; US-PGPUB 2004/07/12 11:01
               359/872.ccls. and "2004"
 BRS
        52
                                          USPAT; US-PGPUB 2004/07/10 18:28
               372/107.ccls. and "2004"
 BRS
        17
                                          USPAT; US-PGPUB 2004/07/10 19:00
               359/260.ccls. and "2004"
        9
 BRS
                                          USPAT; US-PGPUB 2004/07/10 19:00
               372/107.ccls. and "2004"
 BRS
        17
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